SODER-WICK FINE-BRAID® 957-239

Technical Data Sheet

TDS # SW

Soder-Wick Fine-Braid®

PRODUCT DESCRIPTION

Soder-Wick Fine Braid is the state of the art in desoldering. Soder-Wick is especially designed for today's heat sensitive electronic components. Its lighter mass, pure copper braid construction allows for better thermal conductivity, even at low temperatures. Soder-Wick responds as much as 50% faster than conventional desoldering braids. This design minimizes overheating and requires less "contact" pressure for greater operator control. A full range of sizes and flux arrangements are available, including an unfluxed version and a patented No Clean ype. Whatever the requirement, Soder-Wick has the answer.

- Optimized weave design for faster wicking and heat transfer
- Requires little or no post solder cleaning
- No corrosive residues
- Halide free
- Minimal risk of heat damage to components and circuit boards

TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

Soder-Wick Desoldering Braid	
Flux Type:	Grade WW, Type "R"
Cleanup Required:	NO
Military Specifications:	MIL-F-14256F

Size #	Width Inches	Color	Width Metric
#00	.022"	Gold	.56mm
#01	.045"	Gold	1.14mm
#02	.055"	Gold	1.40mm
1	.030"	White	.76mm
2	.060"	Yellow	1.52mm
3	.080"	Green	2.03mm
4	.110"	Blue	2.79mm
5	.145"	Brown	3.68mm
6	.210"	Red	5.33mm

TYPICAL APPLICATIONS

Soder-Wick desoldering braid safely removes solder from:

- Thru-Hole Components
- Surface Mount Device Pads
- BGA Pads
- Micro Circuits
- Terminals
- Lugs and Posts
- Identification Script

STATIC DISSIPATIVE PACKAGING

Static dissipative packaging is available on 5 and 10 foot bobbins. The SD bobbins qualify as electrostatic discharge protective per DOD Standard 1686 and DOD Handbook 263. Meets the static decay rate provision of MIL-B-81705C.

SODER-WICK FINE-BRAID® The State of The the Art in Desoldering™